

WAFER LEVEL PACKAGE, MULTI-PACKAGE STACK,  
AND METHOD OF MANUFACTURING THE SAME  
Application No. 10/665,630 – Attorney Doc. No. SEC.1064  
Inventors: Hyeong-Seob Kim et al.

FIG .1

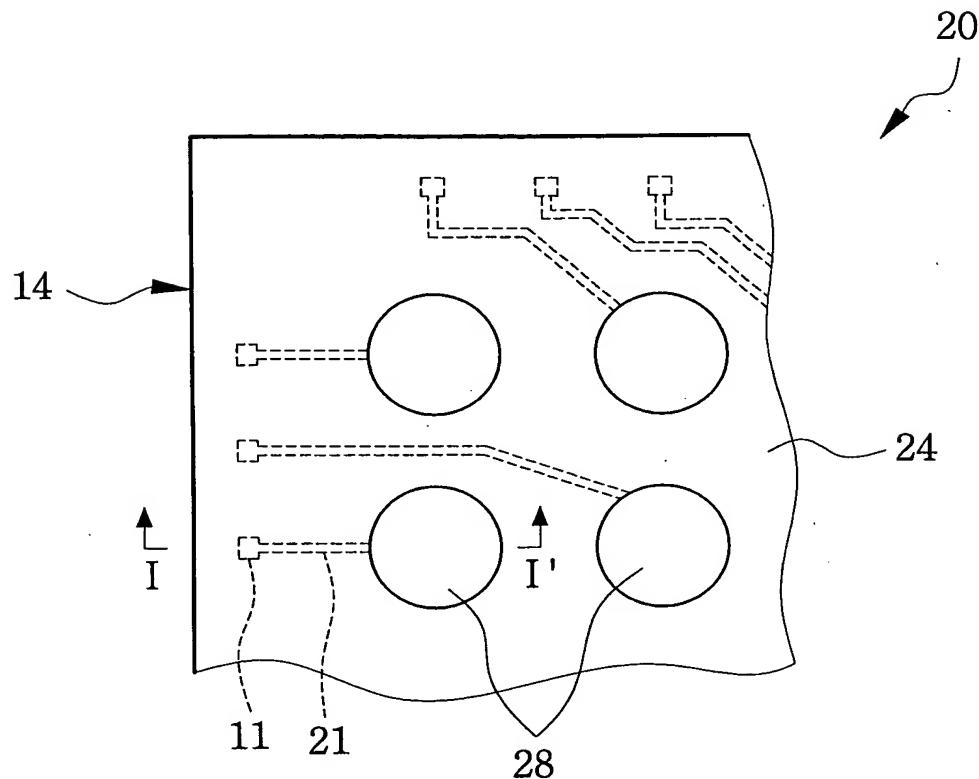


FIG .2

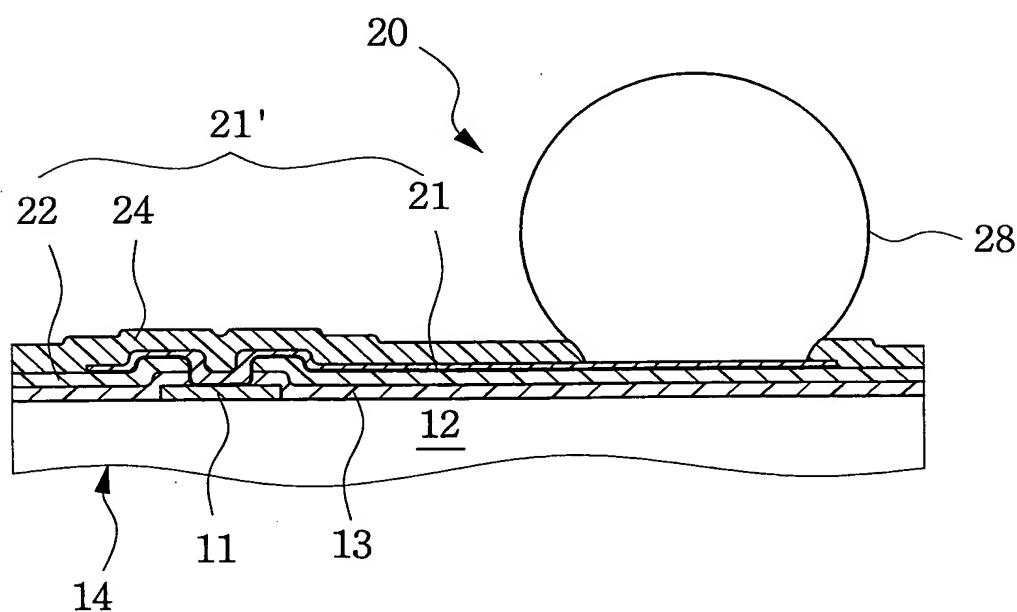


FIG .3

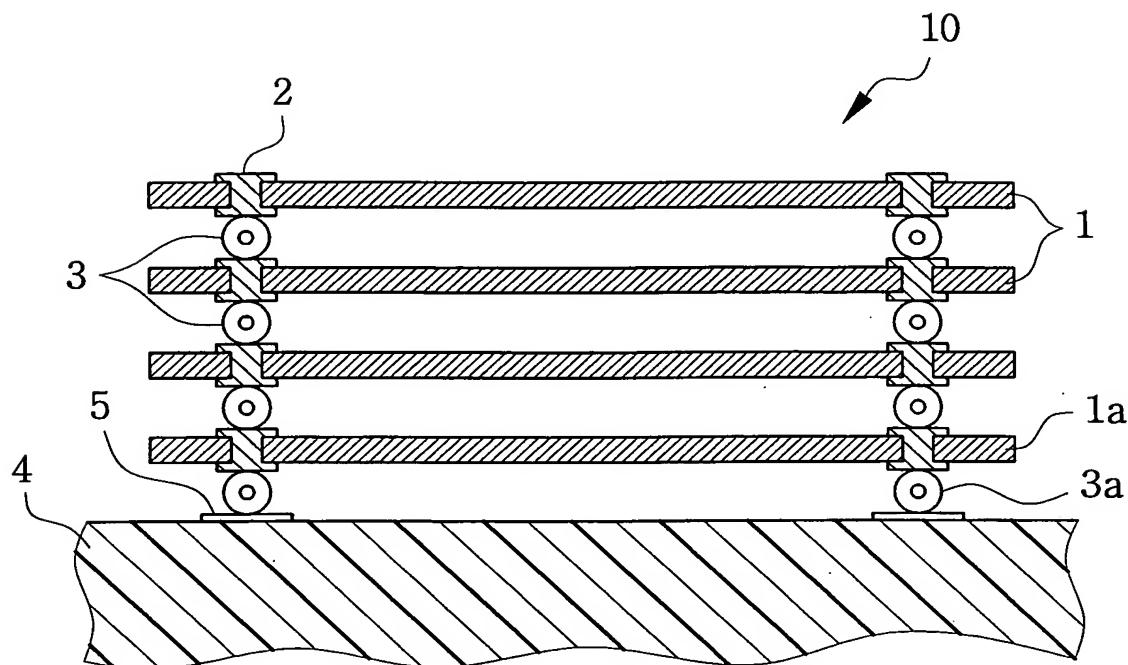
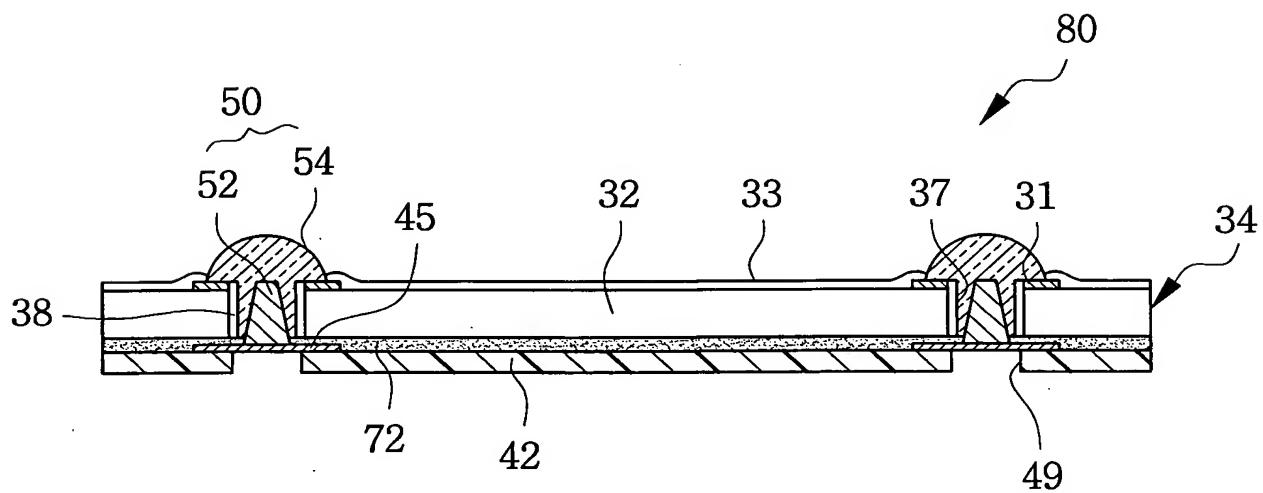


FIG .4



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FIG .5

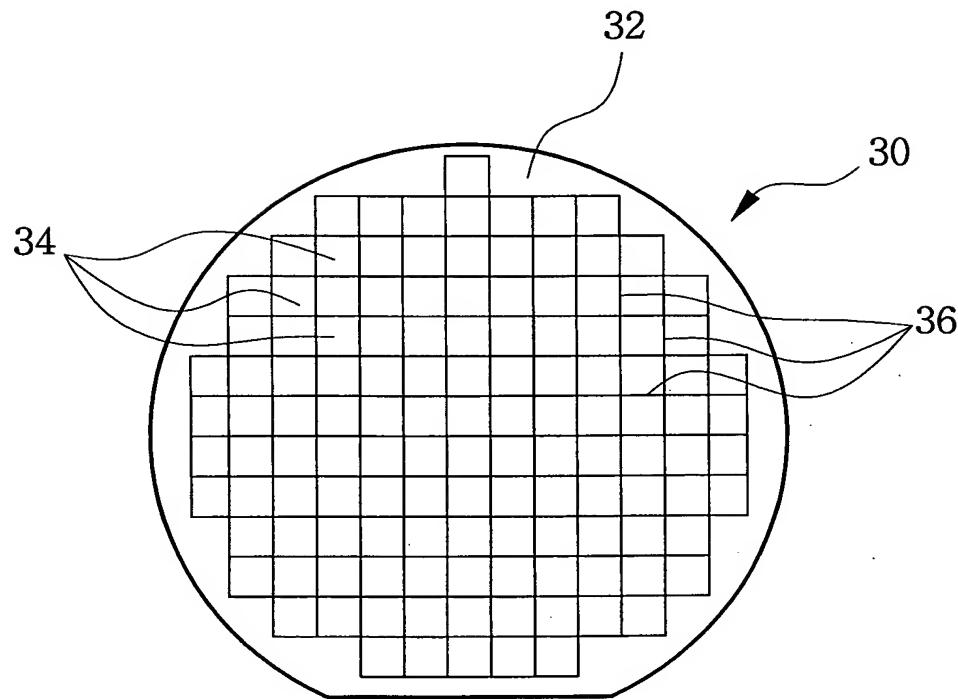
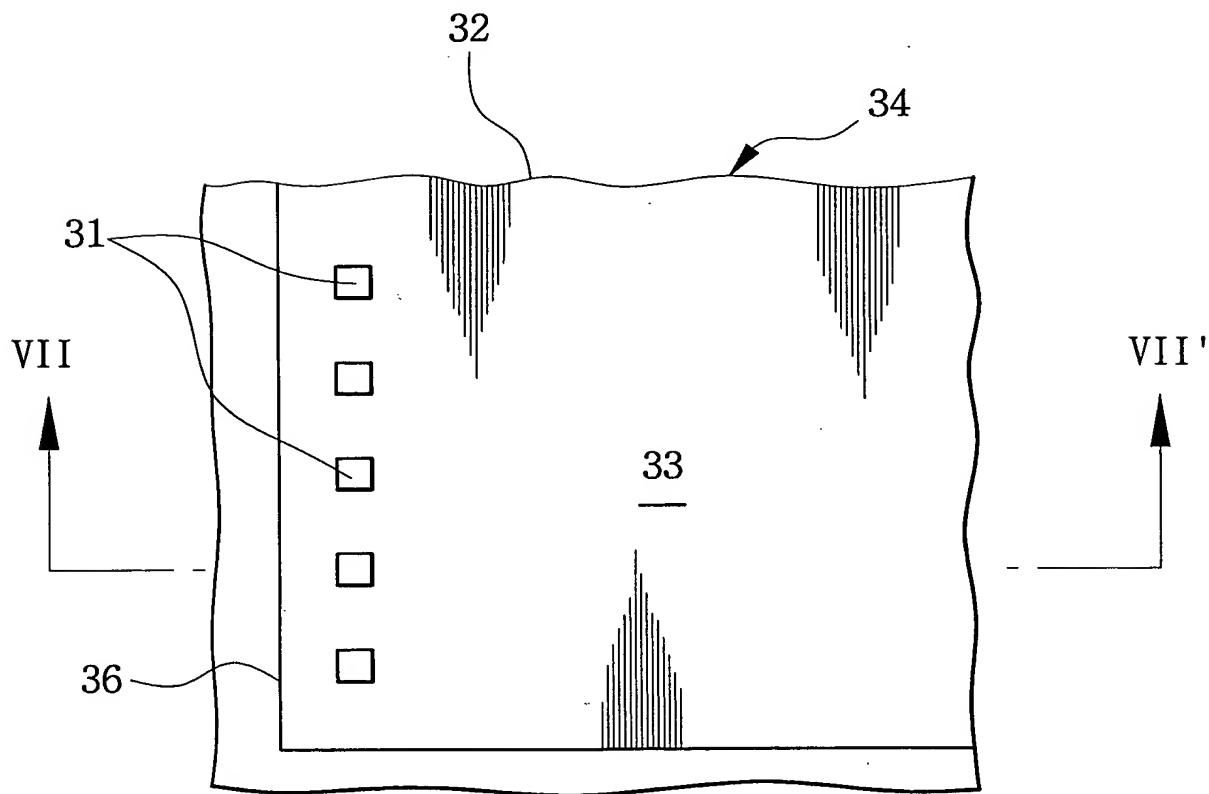
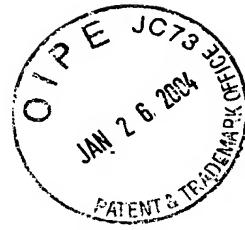


FIG .6





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FIG .7

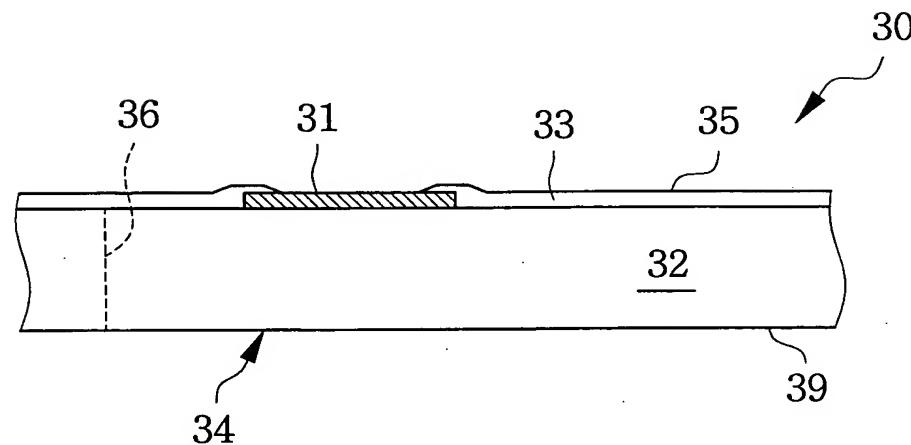
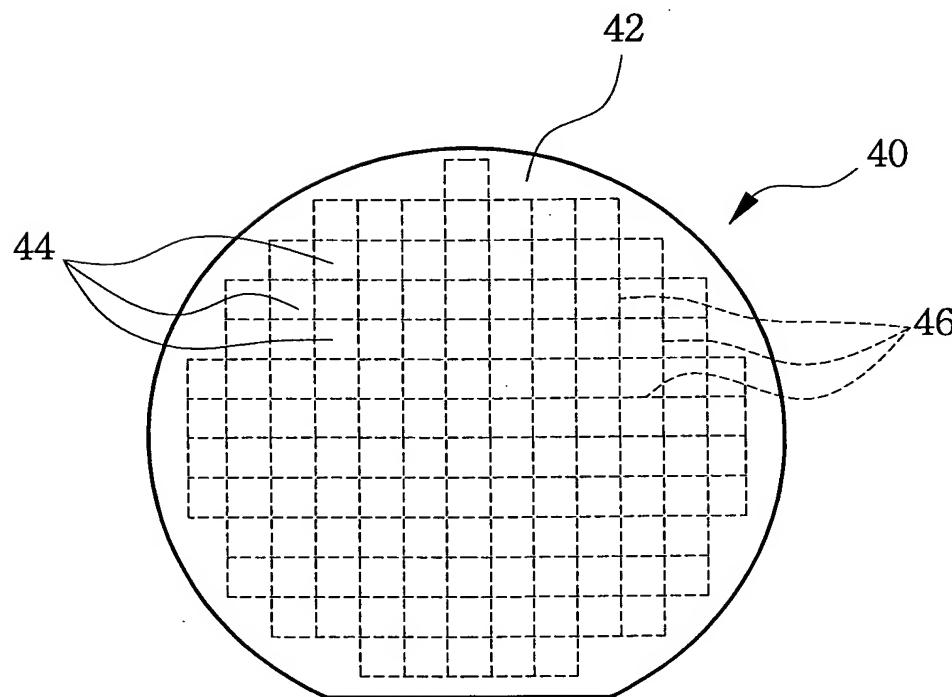


FIG .8



WAFER LEVEL PACKAGE, MULTI-PACKAGE STACK,  
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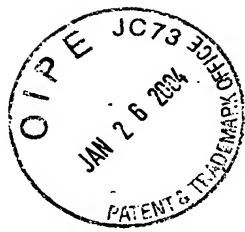


FIG .9

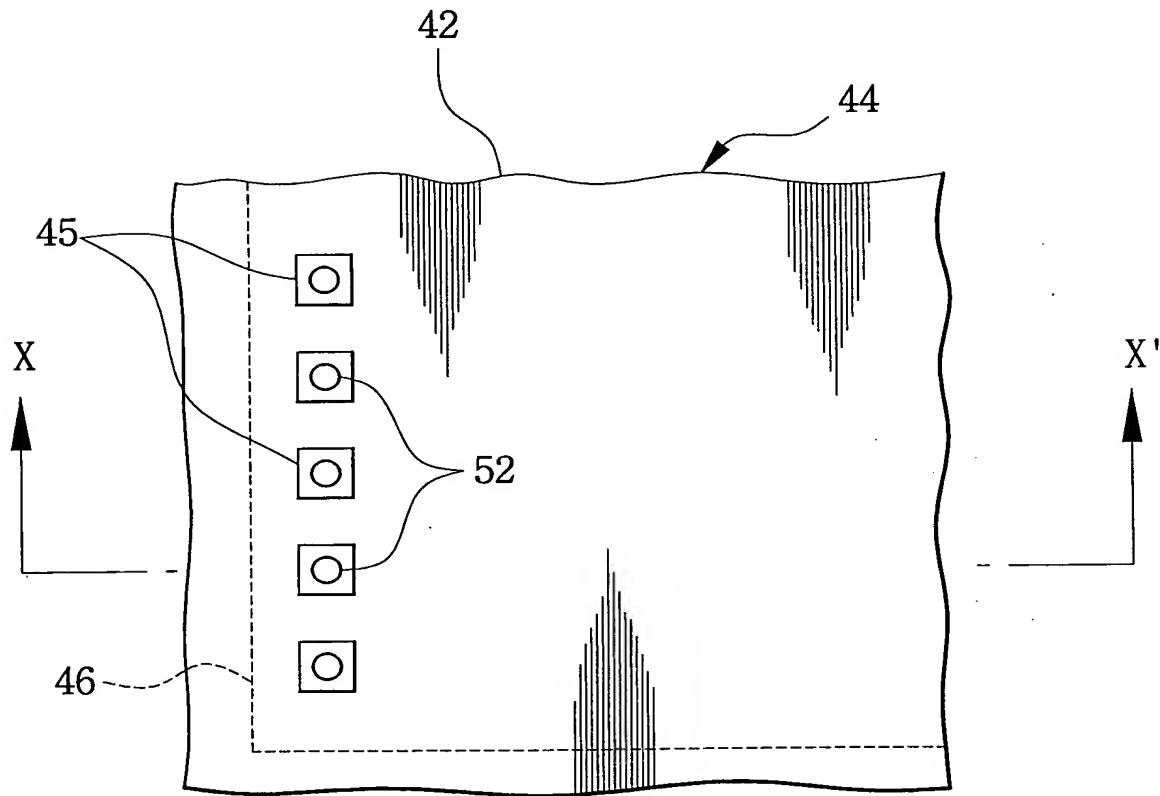
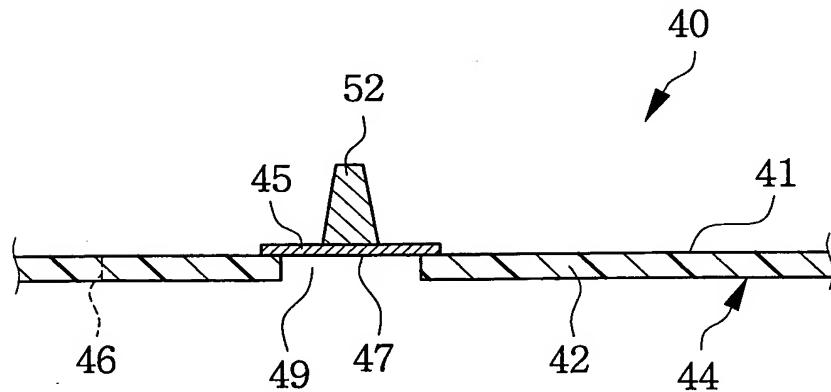


FIG .10



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FIG .11

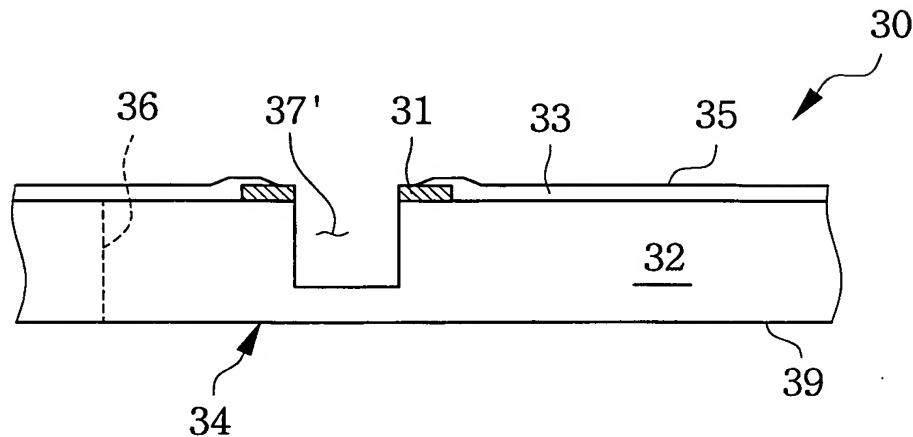
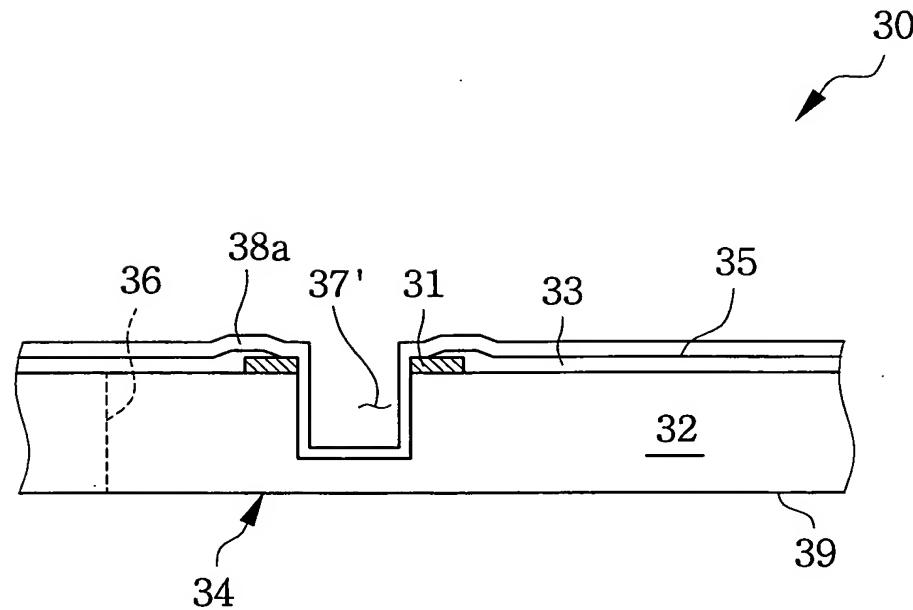
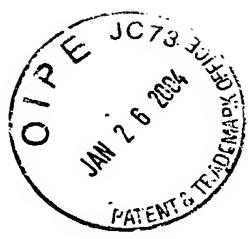


FIG .12a





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FIG .12b

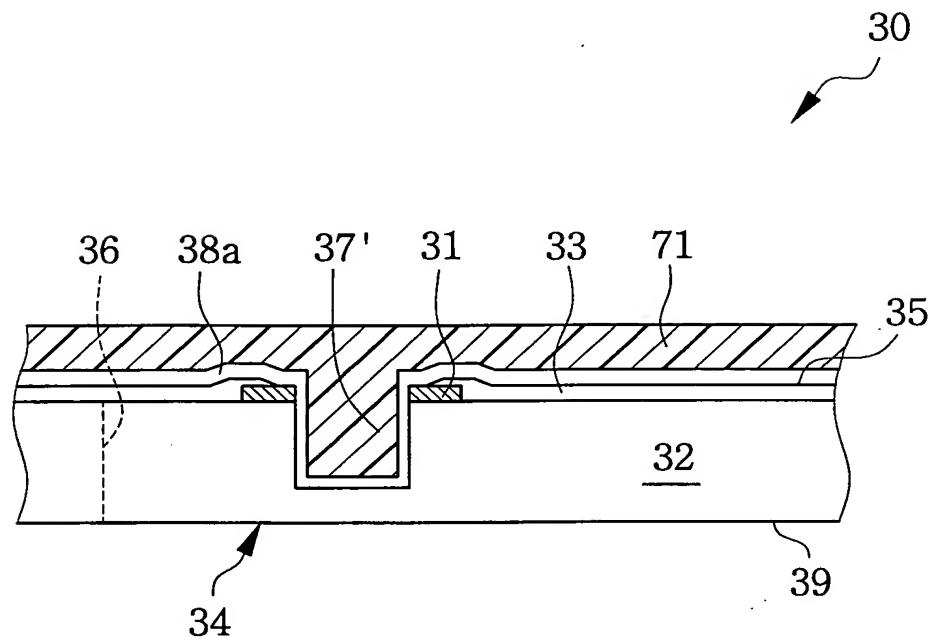
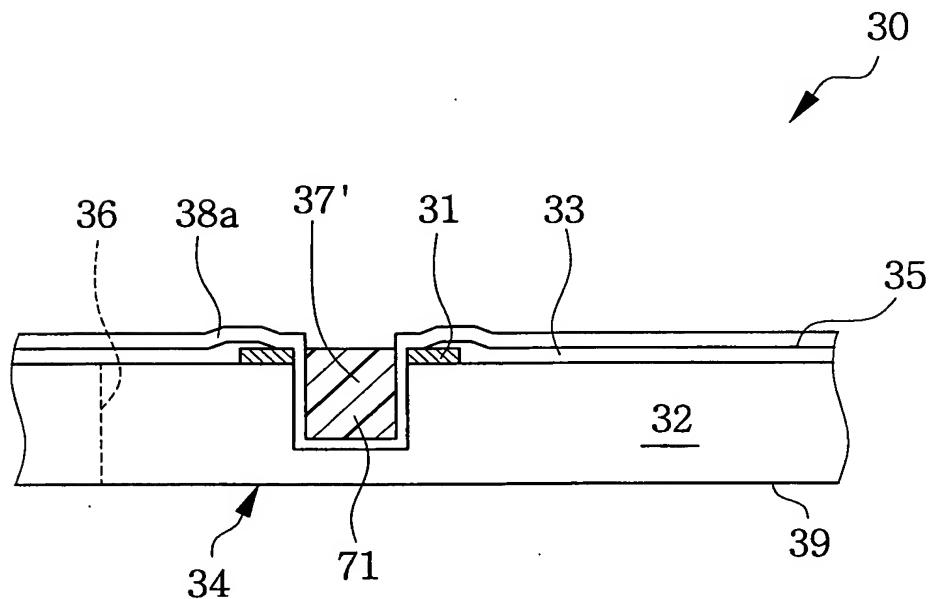


FIG .12c



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FIG .12d

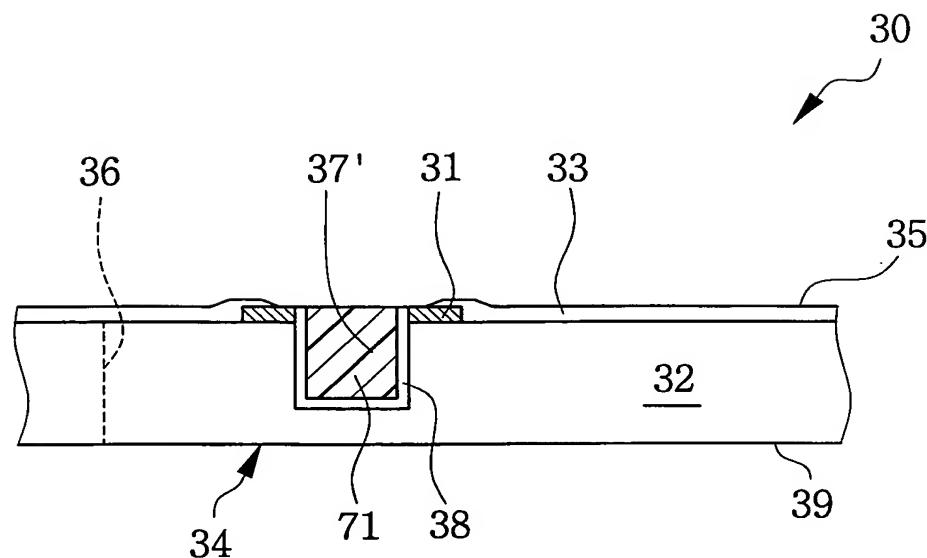
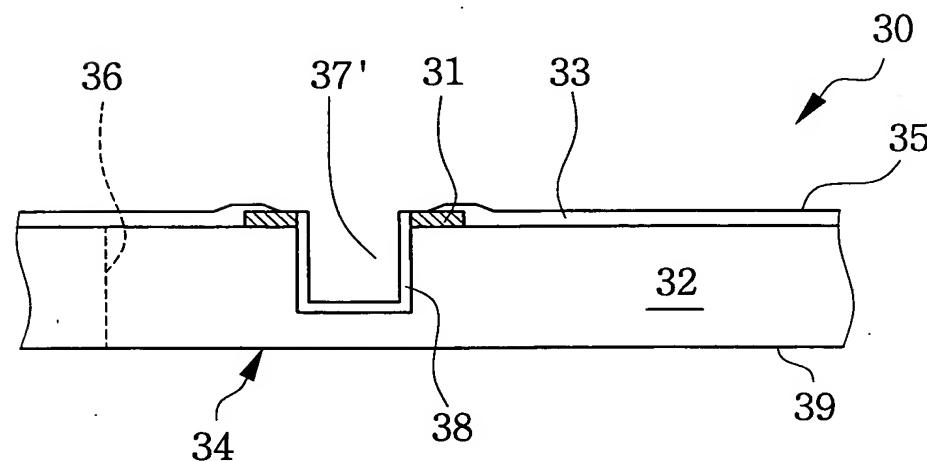
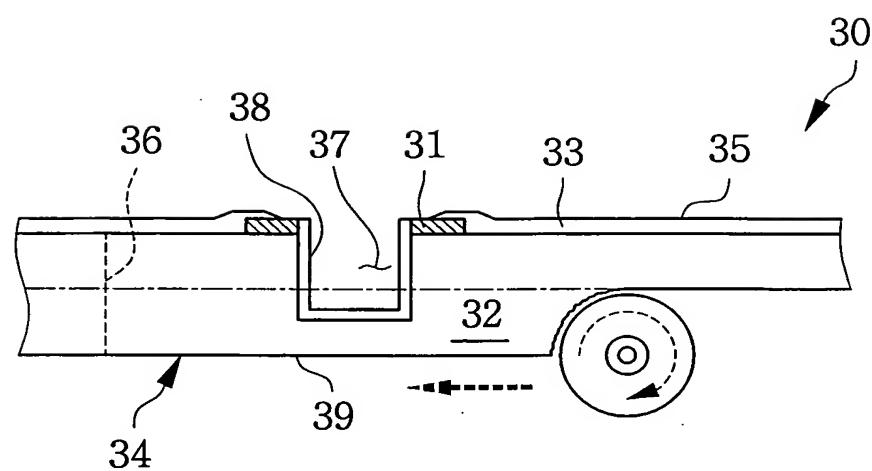


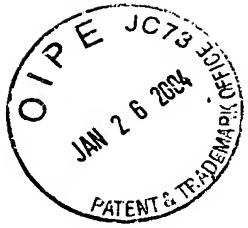
FIG .12e



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FIG .13





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FIG .14

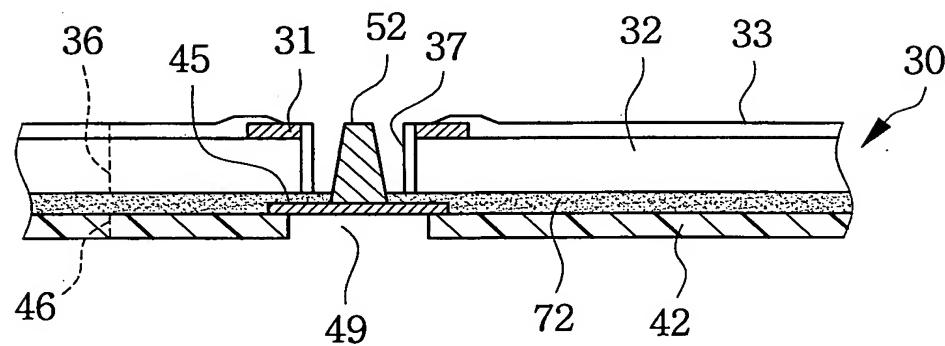
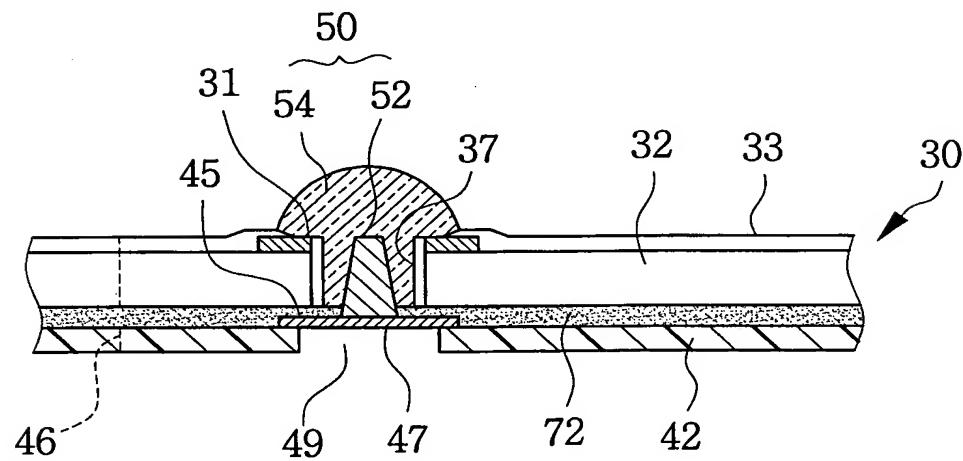
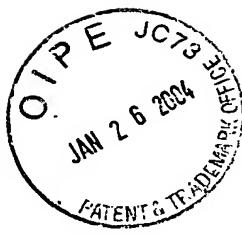


FIG .15





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FIG .16

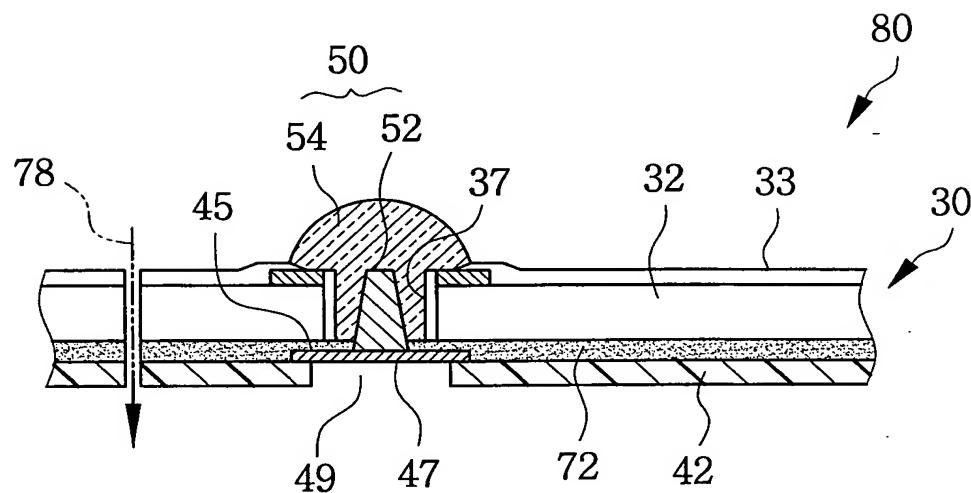
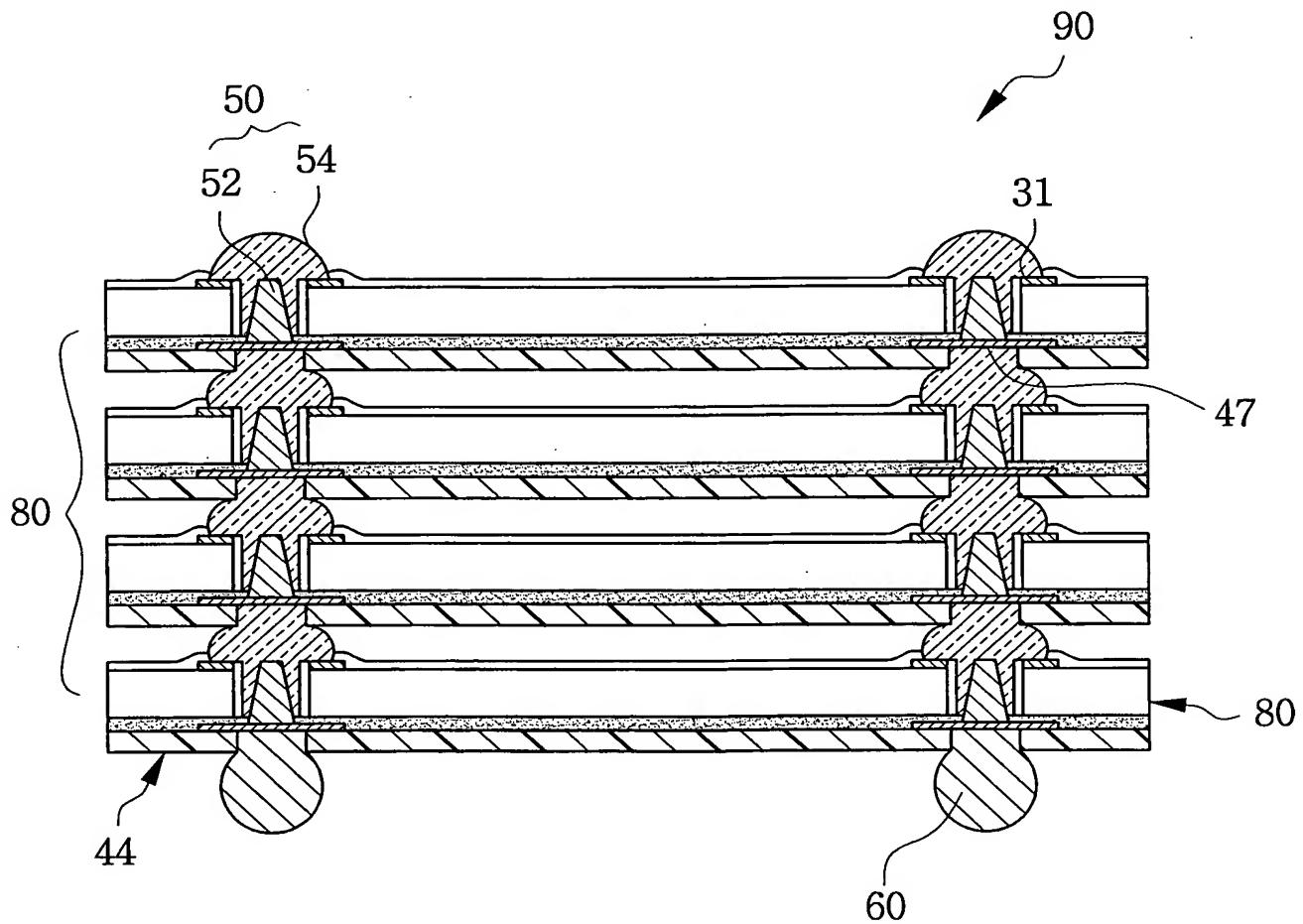


FIG .17





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FIG .18

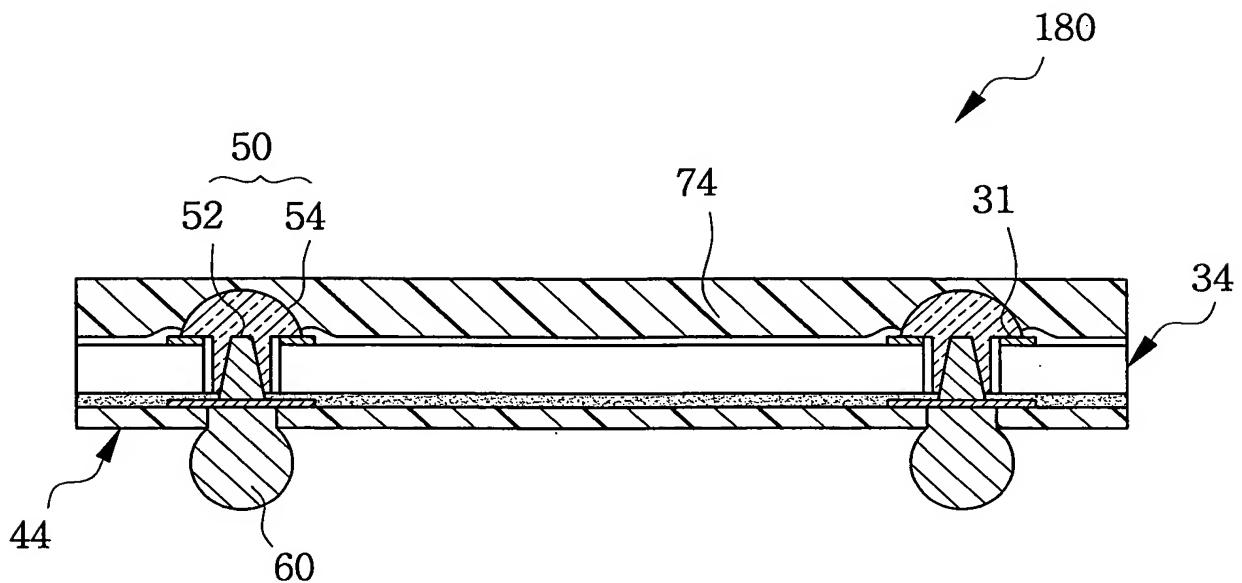
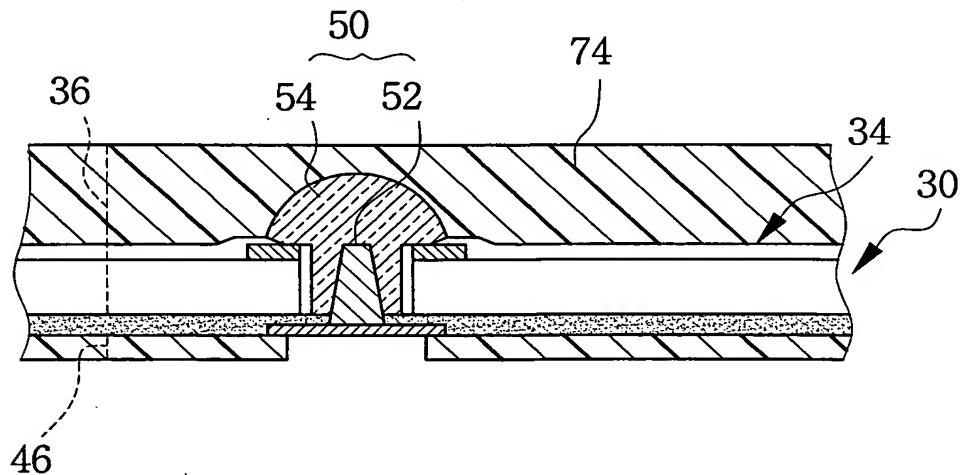


FIG .19



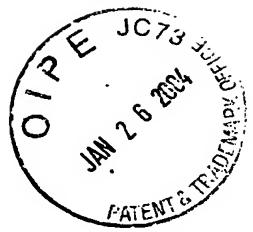


FIG .20

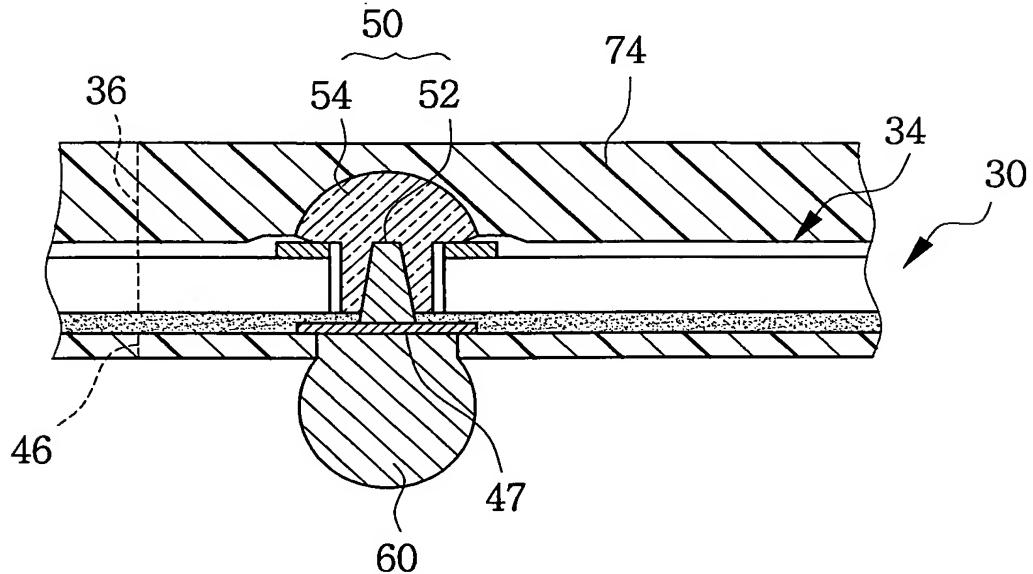
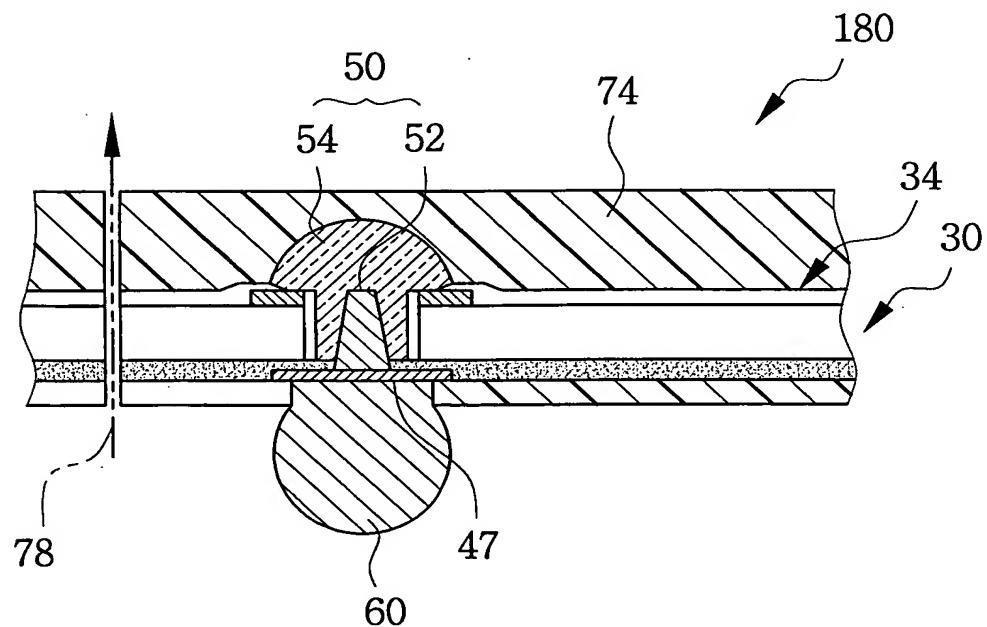


FIG .21





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FIG .22

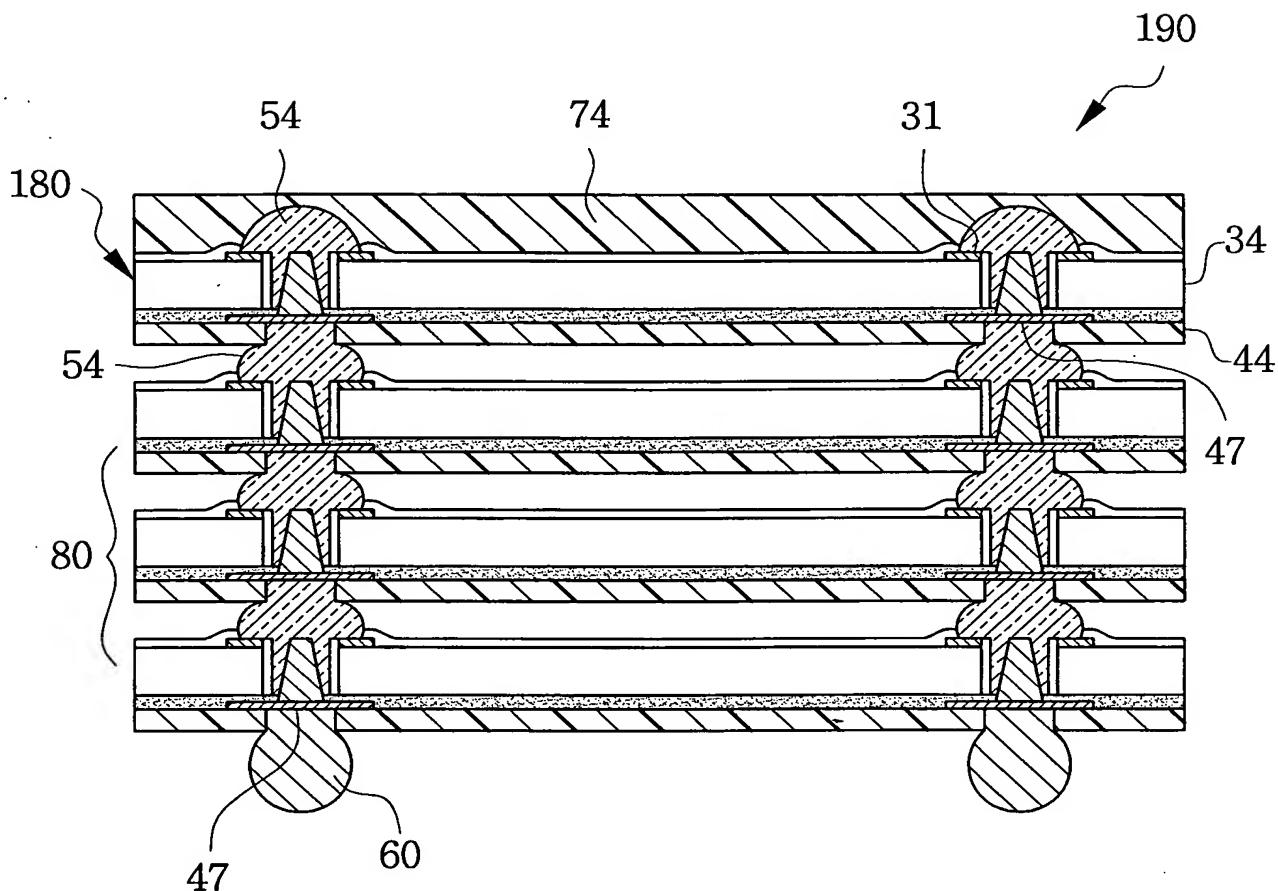
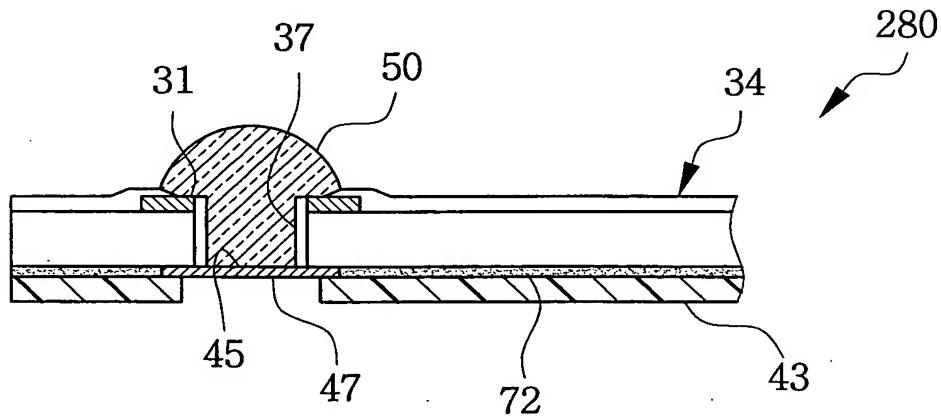
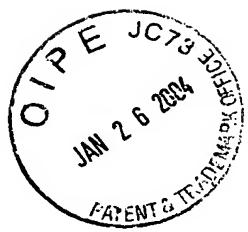


FIG .23





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FIG .24

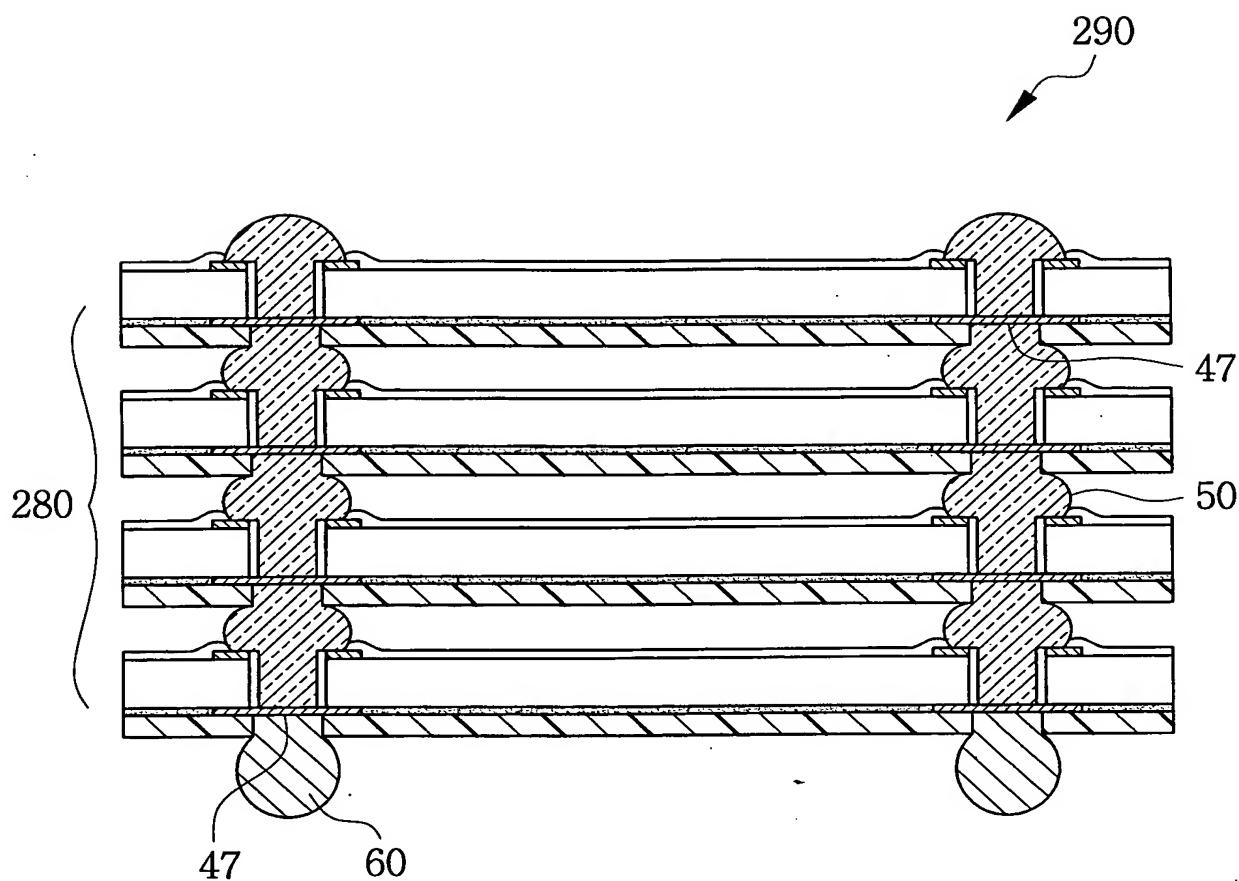
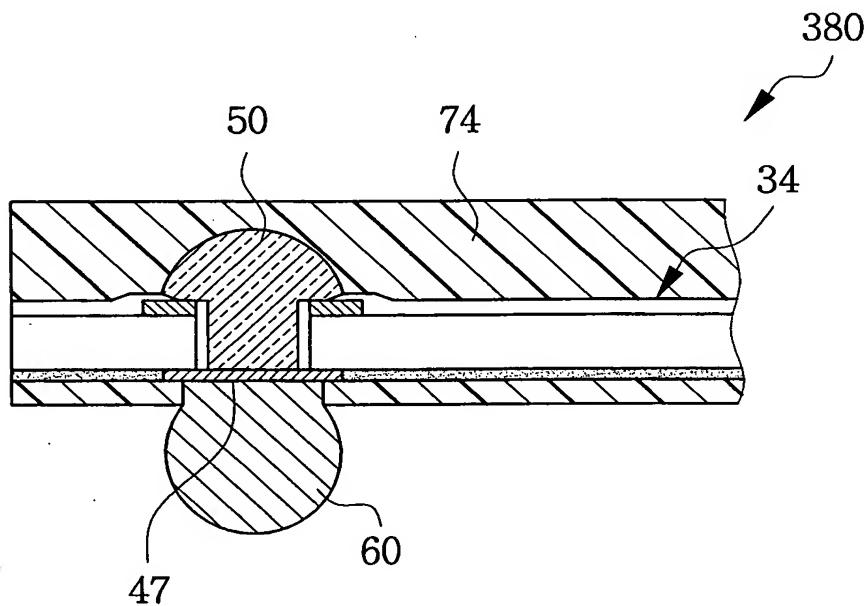


FIG .25



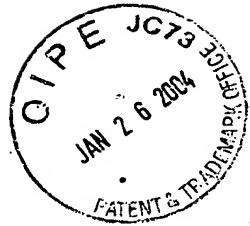


FIG .26

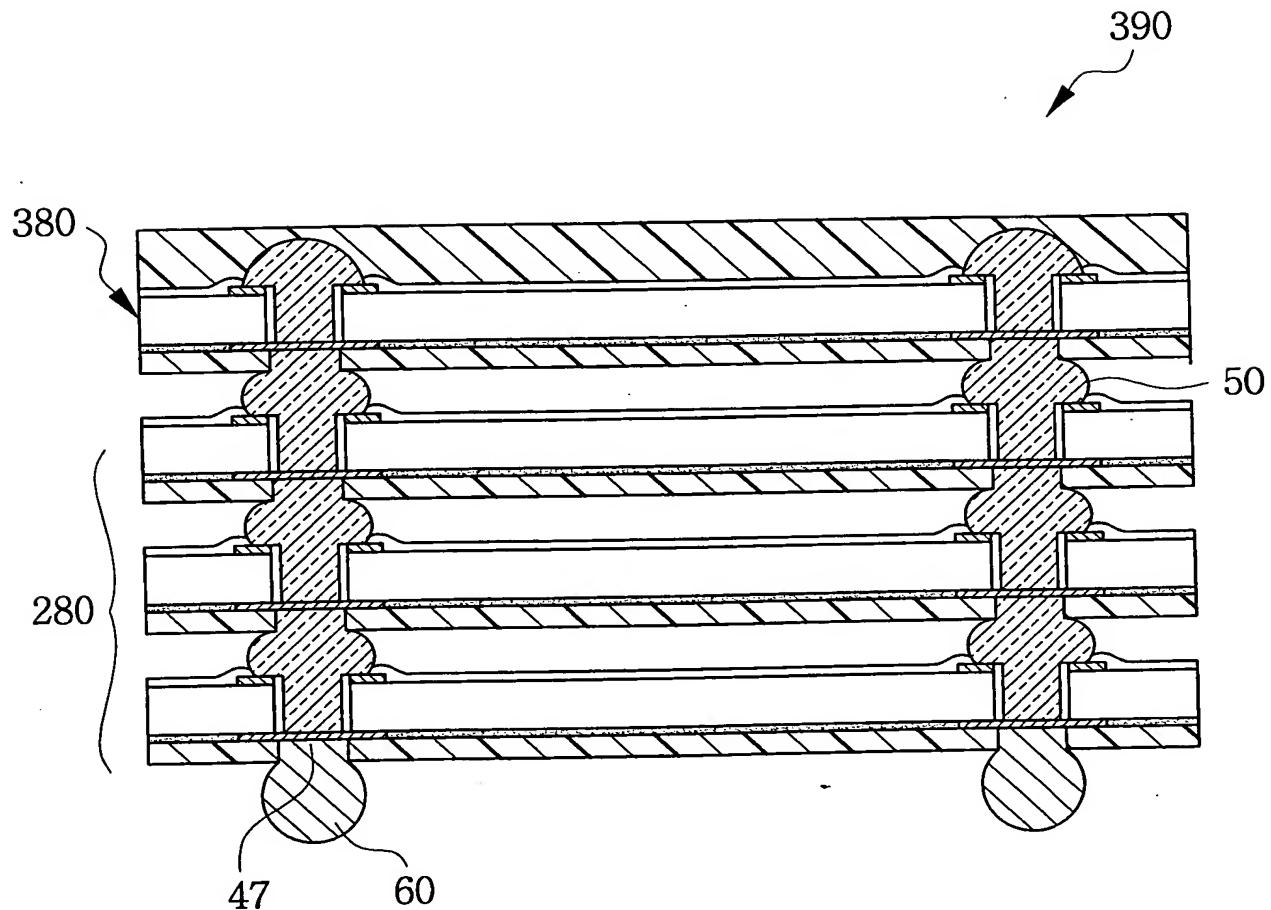
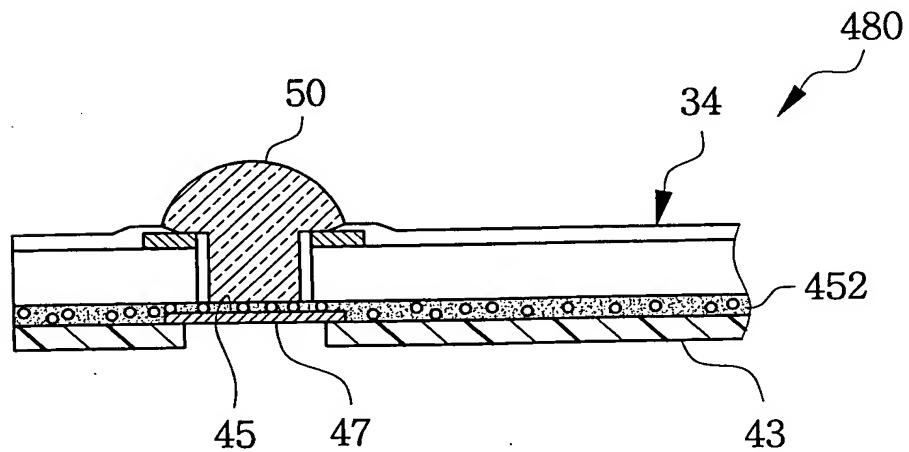
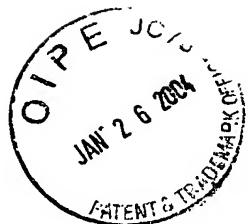


FIG .27





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FIG .28

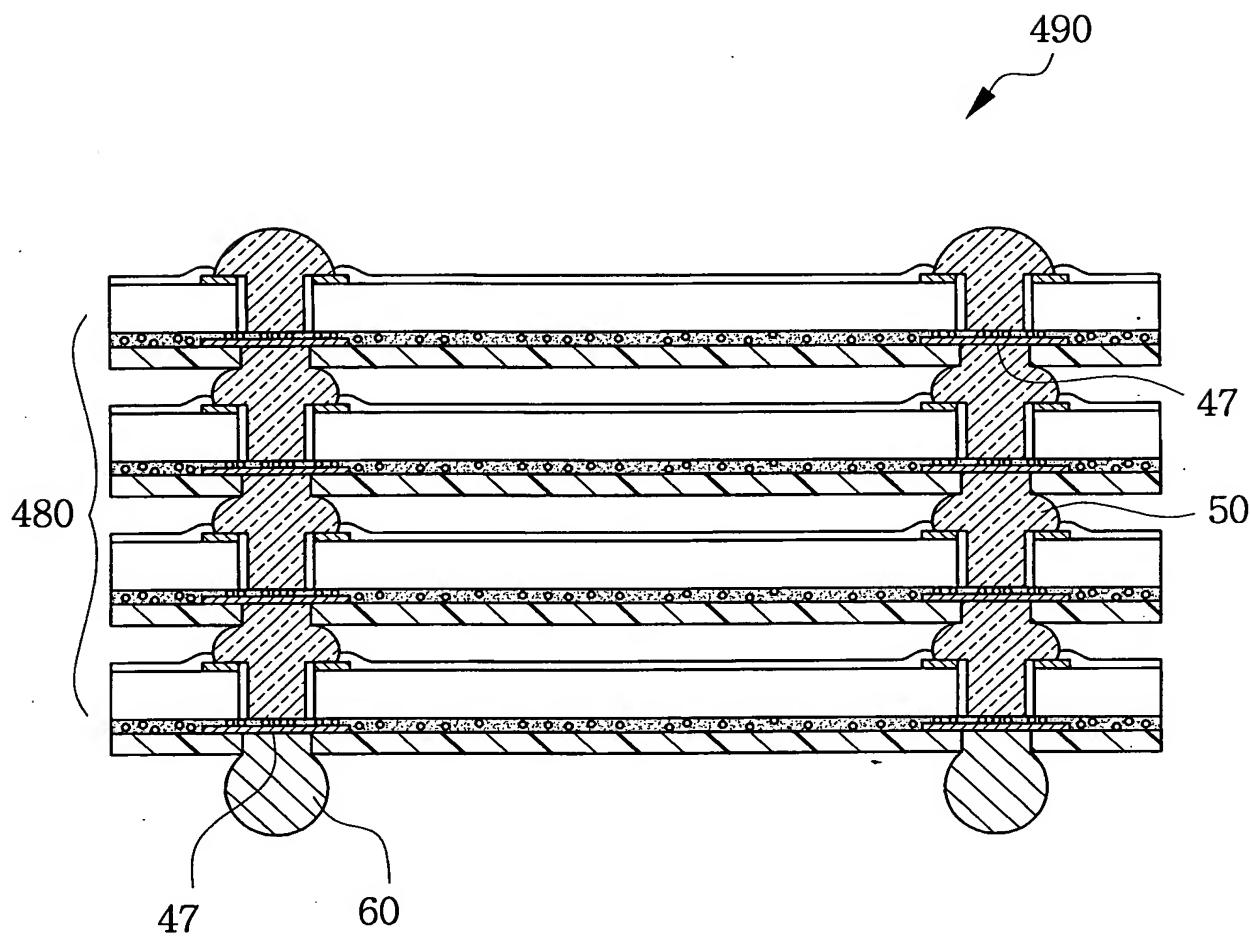
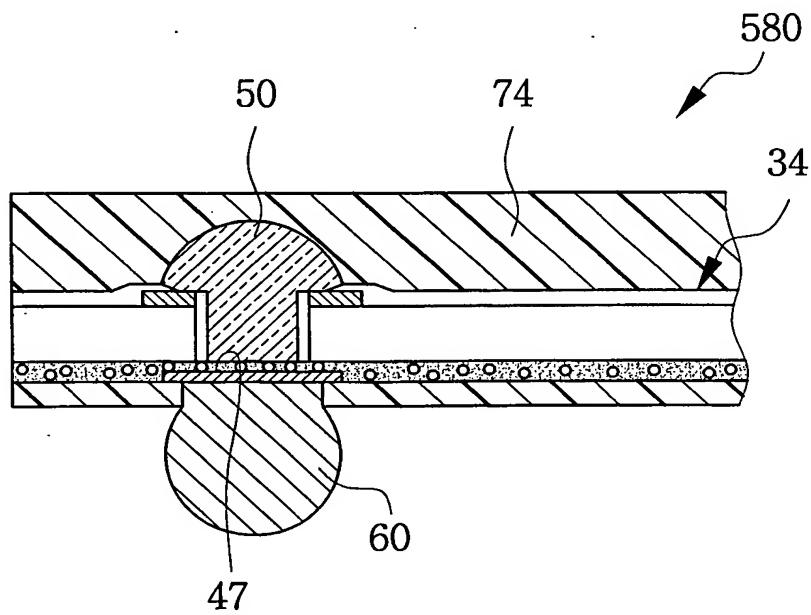


FIG .29



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FIG .30

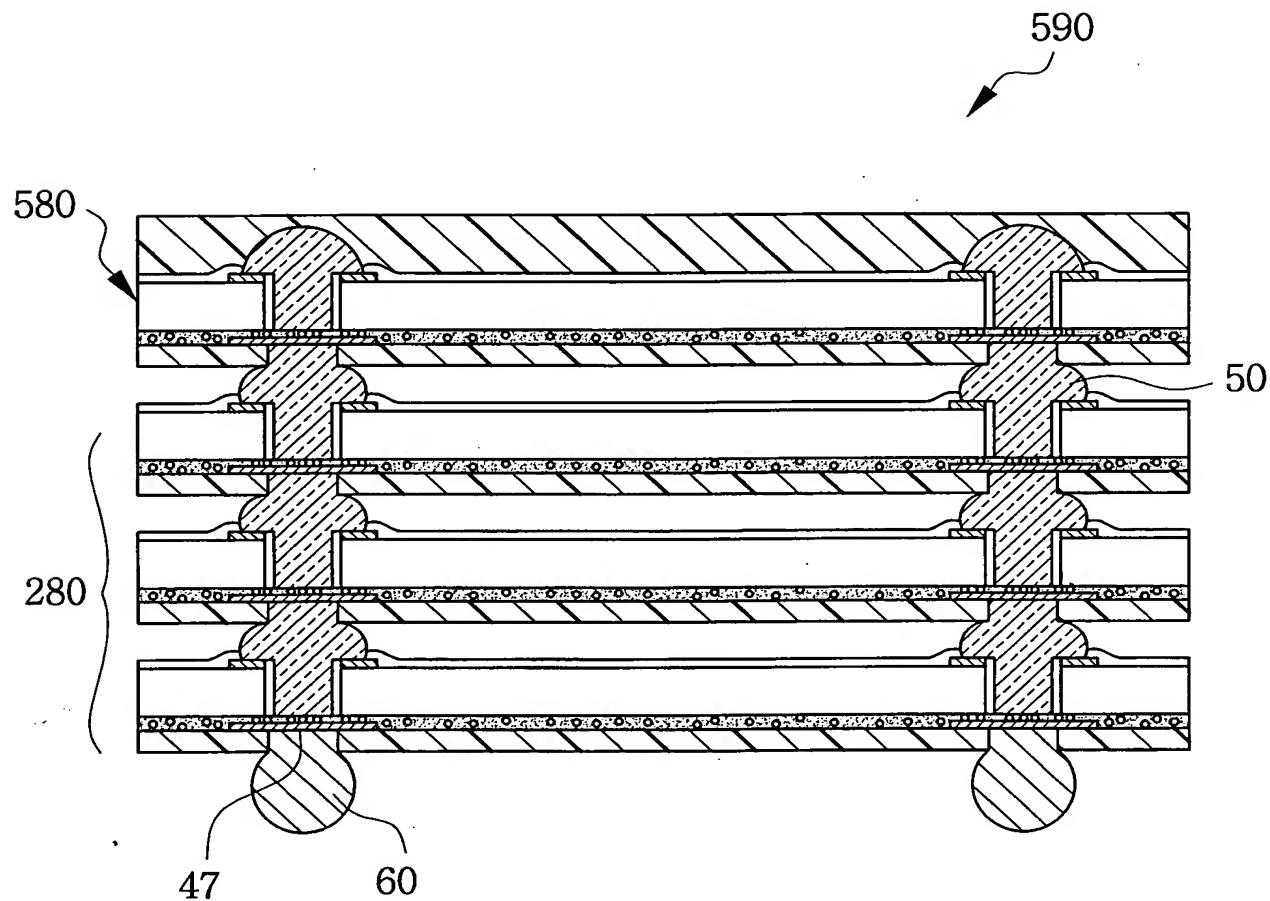


FIG .31

